

**IN THE SPECIFICATION:**

**Paragraph beginning at line 9 of page 5 has been amended as follows:**

Also, with narrowing a pitch of the connection terminals, a large number of pins can be arranged at high density within an area conventionally used. An outline of the wiring portion and the bonding portion are artificially checked using a microscope or the like. In recent years, in order to electrically conduct determination of a defect such as a short circuit or a disconnection, a test land is provided for each of the connection terminals. Because the test land connected with each of the connection terminals is unnecessary as an electronic part mounted on a display device, the test land is separated from each of the connection terminals of the FPC or the TCP and discarded. As the number of pins increases, an arrangement area of the test lands becomes larger than an area of the TCP or the FPC which are actually used, thereby increasing ~~pressure on member~~ costs of the TCP and the FPC. This is a third problem.

**Paragraph beginning at line 5 of page 8 has been amended as follows:**

A semiconductor device according to the present invention includes a flexible printed circuit and a

semiconductor chip mounted on the flexible printed circuit. The flexible printed circuit includes a plurality of land-shaped connection terminals arranged in a step form or a grid form. Further, the flexible printed circuit has a connection terminal portion. In the connection terminal portion, an insulating film is provided to a wiring connected with the respective land-shaped connection terminals. Further, the land-shaped connection terminals are commonly used as terminals for an electrical test.

**Paragraph beginning at line 1 of page 12 has been amended as follows:**

A terminal structure of this embodiment relates to a structure in which test terminals and specific connection terminals are commonly used and arranged in a step shape (i.e., a stepped configuration) or a grid shape (i.e., a grid configuration). Fig. 7 is a partially enlarged view showing a layout of connection lands in which five-step connection terminals having a pitch of 54  $\mu\text{m}$  are provided. Fig. 8A is an entire view of a carrier tape in which such a TCP is provided. Fig. 10 shows lands of the TCP and terminals of a display panel, which are connected with the lands of the TCP. In addition, Fig. 9 is a schematic view showing that a TCP having connection lands composed of two-step connection terminals is formed by die-cutting it from a carrier tape.

Paragraph beginning at line 8 of page 14 has been amended as follows:

Therefore, the land width increases as the number of steps increases, so that, with respect to a displacement in a transverse direction, the TCP as shown in Fig. 8A, which has the same terminals as in the case of narrow pitch bonding can be supplied by a conventional control method. A ~~product~~ part 20 according to the present invention (Fig. 8A) and a conventional part 21 (Fig. 8B) which are surrounded by the cutting line 19 are identical in shape. However, as compared with the conventional part 21, the used outer size of the part 20 according to the present invention can be reduced by one of sprocket halls 22 40. Accordingly, the area of the base member is reduced, with the result that a cost can be suppressed.